

Ultrasoft Recovery Bridge

Features

Ultrasoft recovery

low I_{RRM}

low VF

V_{RRM}

Special frame design for heat dissipation

Benefits

Reduced EMI

Reduced snubbing

Input Pin (~)	
Input Pin (~)	
Output (+)	
Output (-)	

		XBS30J	XBS30K	XBS30M	
			3		
Reverse Recovery Time. $I_F=0.5A, I_R=1A, I_{RR}=0.25A$	T_{rr}		10		us
			14		
$I^2 t$ rating for fusing (F)	$I^2 t$		98		A^2S
1.5			0		
()			4		
			75		
2			6 12		

Thermal resistance from Junction to case, lead and ambient in accordance with JESD-51.
Unit mounted on 15mm*12mm*1.6mm AL pad attach 195mm*195mm*10mm steel plate

RATINGS AND CHARACTERISTICS CURVES



